DEFENSE LOGISTICS AGENCY

Established 1961

DLA Standards and Specifications Benefit to the Military and Space Users' Community

Components for Military & Space Electronics (CMSE) Conference & Exhibition

April 28-April 30,2026

Muhammad Akbar
DLA Weapons Support Columbus
April 2026

THE NATION'S LOGISTICS COMBAT SUPPORT AGENCY

- The Defense Logistics Agency (DLA) Weapons Support Columbus serves as a cornerstone of the Defense Standardization Program (DSP), managing a vast portfolio of technical documents essential for mission success. Specifically, DLA oversees hundred thousands of production of high-reliability parts and components, including mission-critical, radiation-hardened parts for Department of Defense (DoD) weapon systems and space applications.

- This effort is fundamental to achieving the standardization's primary goals of **Interoperability**, **Reliability, and Affordability** for many years.

- By standardizing parts and equipment, DLA's work enables the seamless sharing of information with mission partners and facilitates the rapid insertion of new technology, thereby ensuring the U.S. maintains its technological superiority for current and future missions.

- DLA Weapons Support Columbus manages 404 FSC, 2.624 million NSN parts and purchase value in 2025: $3.64 Billion.

What is the purpose?

- To provide the warfighter with equipment, parts and materials that are **interoperable, reliable, and technologically superior.**

- Improved operational readiness:
  - Interoperability of systems, subsystems, and equipment among the departments and space agency.
  - Improved logistics support by reducing the variety of supply items (“reduced logistics footprint”).
  - Improved reliability, maintainability, and safety.
  - Improved ability to modernize existing systems through insertion of new technology and parts.
- Reduced ownership costs:
  - Reduced number of nonstandard parts.
  - Improved competition.
  - Use of common processes and open systems.
  - Reduced training costs.
- Reduced cycle time:
  - Uses readily available parts.
  - Reduced procurement lead times.

Common Standardization Part Impact to the Systems

The Impact of a Single Microcircuit

One NSN can have
More than122
Unique WSDCs

Benefits of DLA Standards Parts

Standardized parts are high reliability device, and some are with radiation hardened for military terrestrial/avionics and space satellite applications.

- Non-standard devices often contain pure tin internal and device lead finishes that promote tin whiskers resulting in system failures.
- Non-standard devices are typically more expensive when qualifying for up-screening to acceptable levels in military or space programs.
- Harder to procure because there is no standardization document defining them, are not as reliable due to lack of engineering technical characterization and reliability studies.
- Become often obsoleted by going out of production much sooner than standard military devices, which leads to Diminishing Manufacturing Sources and Materials Shortages (DMSMS) procurement issues.
- DMSMS parts lead to counterfeit parts issue and cost $$$!!!

Sourcing and Qualification (VQ)

Mission:

To establish and maintain a known-good supplier base that have successfully demonstrated their products met the specified performance, quality, and reliability levels via the DoD Product Qualification Program.

Qualification Participants			
Type	Location		Total
	CONUS	OCONUS	
Manufacturer	389	139	528
Dealer	40	0	40
Test Lab	110	10	120
Total	**539**	**149**	**688**

Qualification Requirements:

- Submit Package
- Provide Testing
- Pass Audit
- Submit Retention Reports

- **Provides DoD with pre-approved suppliers of standardized parts**
- **Serves as DoD National Qualifying Activity for assigned FSCs:**
  - Suppliers seek qualification through VQ
  - https://www.dla.mil/LandandMaritime/Offers/Services/TechnicalSupport/SourcingDiv/
- **L&M Counterfeit Mitigation POC**
- **Program Benefits:**
  - Verifies capability and compliance to requirements
  - Improves availability and lead times, plus reduces backorders
  - Lowers life cycle cost
  - One-stop shopping lists of qualified suppliers/parts
  - Provides DoD tremendous audit/testing savings

DLA Weapons Support Columbus Standardization Documents

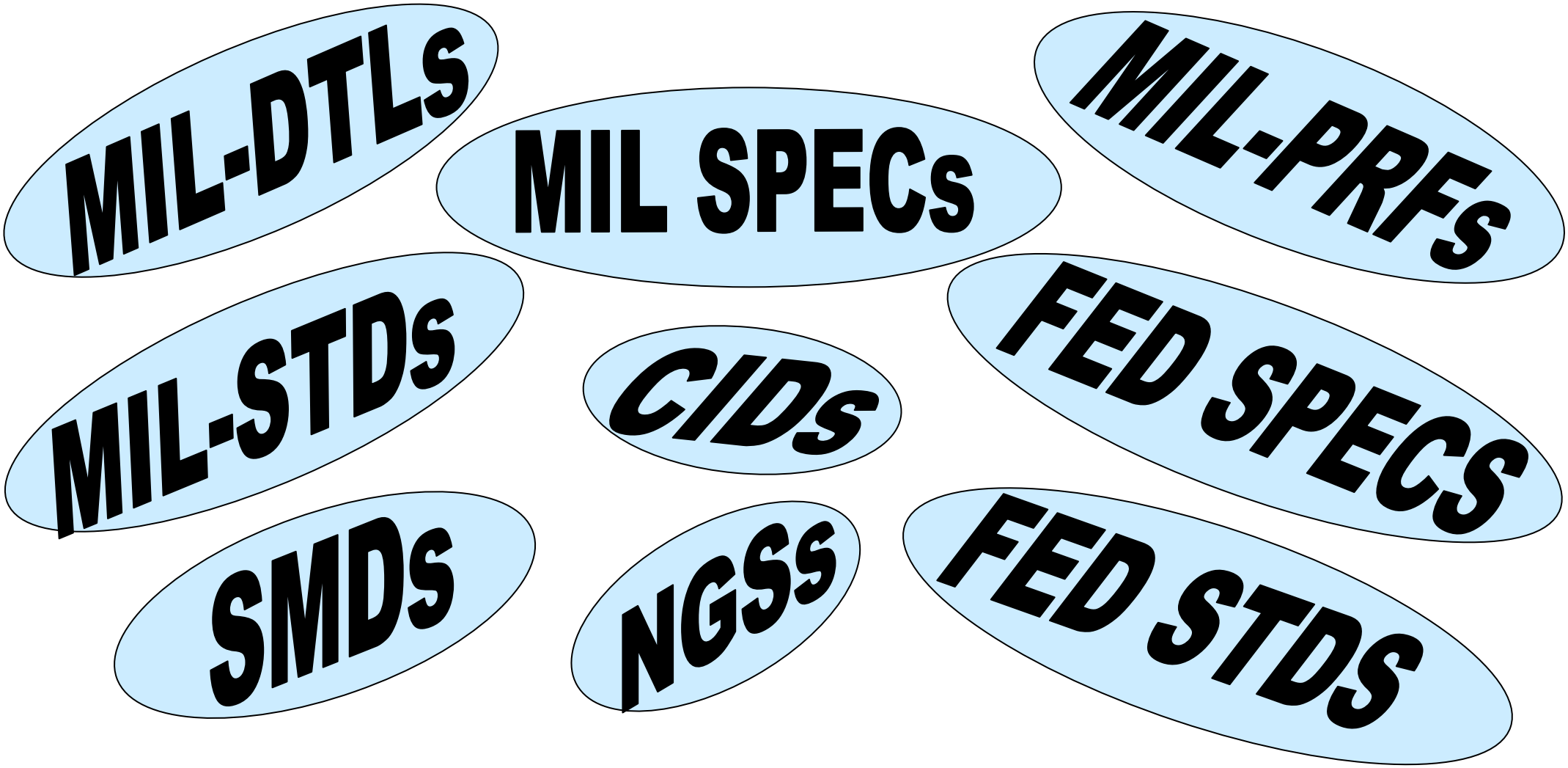
- DLA Weapons Support Columbus, Documents Standardization Division manages 17,565+ Standardization Documents.

- Commodities associated 120 + Federal Supply Class (FSC).
- 275,244 + National Stock Number (NSN) parts for supporting warfighter, military terrestrial, avionic, space, satellite communications, and strategic defense applications.
- The Spec and Standards are new to 60+ years old and serving the warfighter and Space agency with high reliability & quality parts.
- Standards, Spec and Parts can be found at DLA Land and Maritime website: (https://landandmaritimeapps.dla.mil/)
- QPL/QML parts and specifications are published in the ASSIST website : https://quicksearch.dla.mil/

DLA Weapons Support Columbus manages Microelectronics Federal Supply Classes (FSC) notable commodities list:

2530/2910/3020/4010/4820 – Hardware
3010 – Universal Joints
3030 – Belts
4520 – Space heating equipment
4530 - Fuel burning equipment
4720 – Hoses/Fittings
4730 – Fittings
5331 – O ring
5855 – Night vision equipment
5810 – Specialized Equipment, Kits, Outfits/Hand Tools
5821 – Antennas
5895 – RF Mixer
5905 – Resistors
5910 – Capacitors
5915 – Filters
5920 - Fuses
5925 – Circuit Breakers
5930 – Switches
5935 – Connectors, Sockets and Accessories
5945 – Relays
5950 – Transformers/Coils
5955 – Crystals & Oscillators
5960 – Vacuum Tubes
5961 – Semiconductors
5962 – Microcircuits (Monolithic/Hybrids)
5965 – Headsets/Miscellaneous
5970 – Coatings
5980 – Backlight
5985 – RF & Wave Guides
5998 – Printed Wiring Boards
5999 – Miscellaneous
6010/6015 – Fiber Optic Cables
6060 – Fiber Optics
6069 – Miscellaneous Fiber Optic Components
6145 – Wire/Cable
6625 - Indicators

How Do You Know If You Are Using the Program?

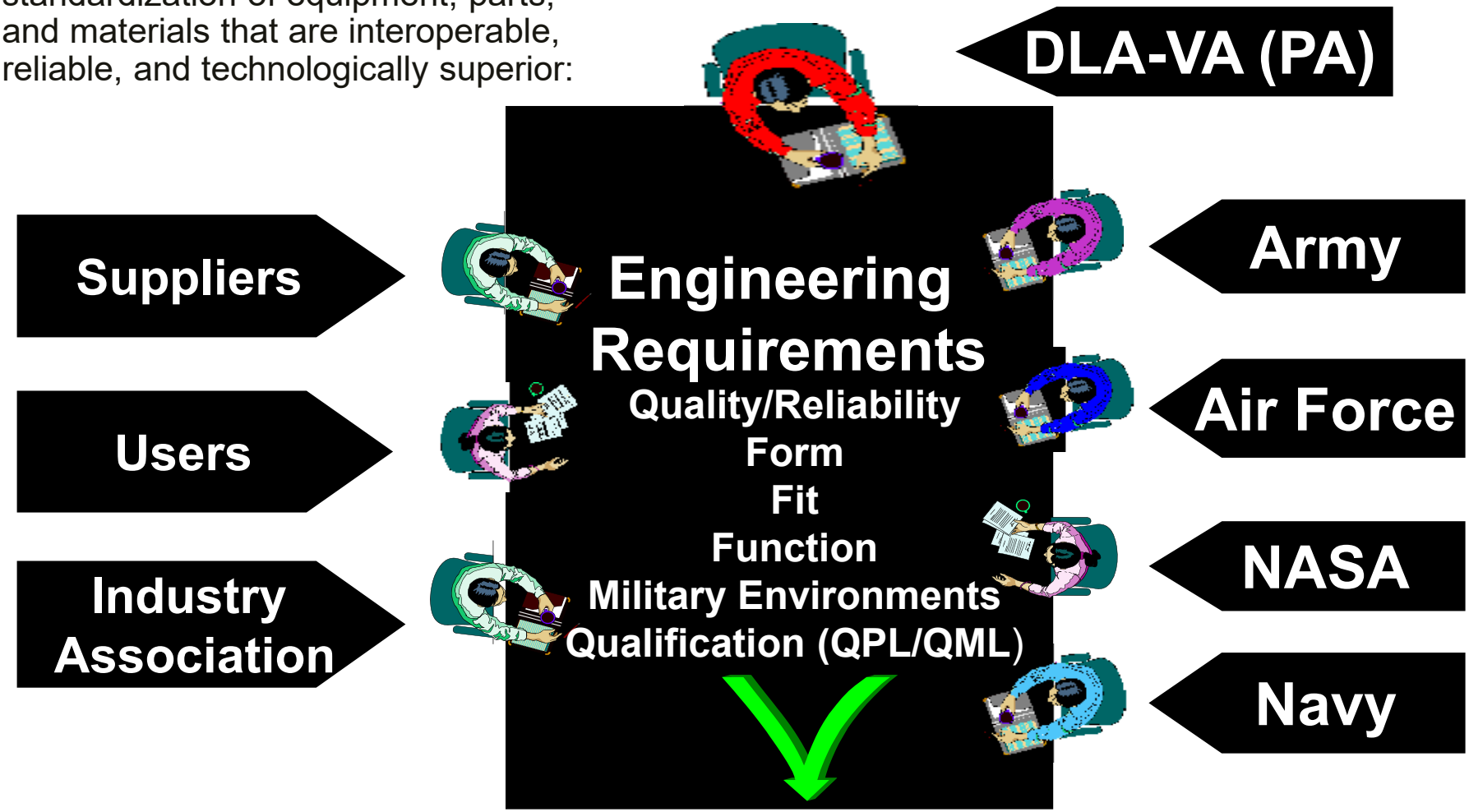


If You See Any of These, You Are Using the Program

Types of Standardization Documents

- **Military Performance spec.:** e.g., MIL-PRF-19500 (Semiconductors)
- **Military Detail Spec:** e.g., MIL-DTL-38999 (Connector)
- **MIL Specifications**: Are used to procure a specific part/product MS Documents: e.g., MS 28760 (Fitting)
- **Standard Microcircuit Drawings (SMDs):**e.g., 5962-87525 (Microcircuit)
- **Military Standards Test Method** : MIL-STD-202, MIL-STD-750, MIL-STD-883 Interfaces: MIL-STD-1560 , MIL-STD-790 (High Reliability) and MIL-STD-1580 DPA .
- **Commercial Item Descriptions (CIDs):** e.g. A-A-55569 (Fuses).
- **Vendor Item Drawings (VIDs):** e.g. V62/25605 (Microcircuits).
- **DLA Drawings :** Covers 23 FSC commodities.
- **Nongovernment Standards (NGSs):** Developed by National Standards Bodies: SAE, EIA, JEDEC, ASTM, ESDA, IPC

- To provide the warfighter with standardization of equipment, parts, and materials that are interoperable, reliable, and technologically superior:



Standardization Document

DLA Land and Maritime Preparing Activity (PA) Document Coordination with Industry Partners

JEDEC
Global Standards for the Microelectronics Industry

- JEDEC JC-13 (Manufacturers)
- Triannual conference

JEDEC Task Group support
Chair: JC-13 Manufacturer
Co-chair: CE-12 User
Biweekly Teleconference

SAE INTERNATIONAL

SAE CE-11/CE-12 (Industry Users, Primes, Subs)
Triannual conference

NEPAG
OneSpace Community
Pursuing Excellence in Parts, Materials, Processes
Since 2000
NASA Electronic Parts Assurance Group

weekly teleconference

NEPP
NASA Electronic Parts and Packaging Program

NASA

AEROSPACE

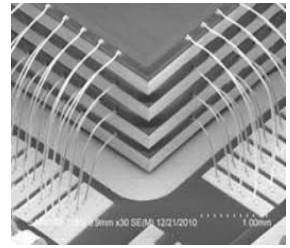
GWG

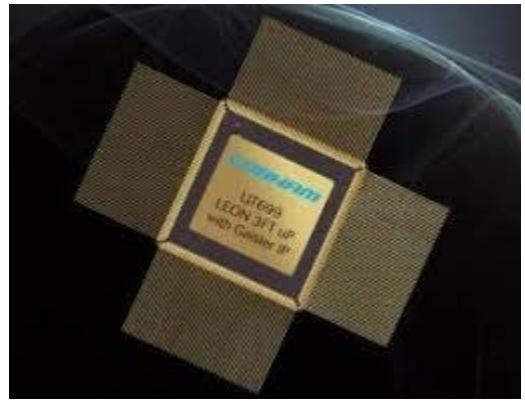
Government Working Group
Including:
ARMY, NAVY, AIR FORCE, NRO, NASA,
Biweekly Teleconference

For Space microcircuits, DLA, NASA and military services, Aerospace Corp. form the Qualifying Activity (QA).

DLA Weapons Support Columbus Microcircuits program

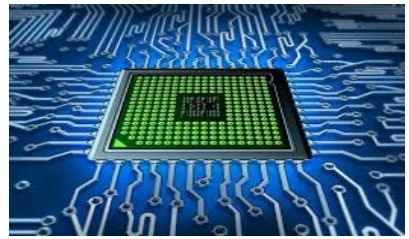
- FSC 5962: Microcircuits device program supported by:
- 55+ qualified manufacturers
- 26+ certified fabrications (off-shore and on-shore)
- 12+ assembly facilities
- 4,274+ QML SMD
- 817 Vendor Item Drawing (VID) (some are RHA VID parts)
- 29,217+ QML devices including Logic, Amplifier, A/C,D/C Converter, Memory, Microcontroller, Microprocessor, ASIC, FPGA
- 10,296+ Radiation Hardness Assurance (RHA) devices for supporting warfighters, DoD weapon systems, and NASA space satellite mission.
- Over 11,600 SMD parts and 439 weapons sub-systems are using with SMD Registered Users program.
- DLA purchase value in 2025: $ 38.66 million





Standard Microcircuit Drawing (SMD)

Standard Microcircuit Drawings (SMDs): A Standard Microcircuit Drawing (SMD) is a document that depicts the Government's requirements for an existing commercial microcircuit, tested for a military application.



Benefits of the SMD:

- To prevent the proliferation of contractor-developed drawings SCD/AID.
- SMDs cover off-the-shelf high-reliability microcircuits targeted for military and space applications.
- Standardized document is DLA/DoD procurement vehicle and provides substantial savings in both acquisition and logistics.
- The manufacturer shall demonstrate compliance to the QML certification and qualification requirements .
- Microcircuits in compliance with MIL-STD-883, MIL-PRF-38535 or MIL-PRF-38534

- **See DLA website for a list of documents that are currently available.**

  - https://landandmaritimeapps.dla.mil/Programs/MilSpec/SmdOverview.aspx

  - https://landandmaritimeapps.dla.mil/programs/Smcr/

Standardized Application Specific Integrated Circuits (ASICs)

ASICs Background: This program was started under MIL-PRF-38535. All Qualified Manufacturer's List (QML) parts must be specified on a Standard Microcircuit Drawing (SMD). Thus, the QML ASICs had to be covered by SMDs.

- ASIC drawings are split up into two categories:
  - **Fully characterized ASICs SMDs** contain an "A" in the SMD number, e.g., 5962-97A01
  - **GATE ARRAY SMDs** contain a "B" in the SMD number, e.g., 5962-97B01.

Note: These types of SMDs by their design are unique and restricted to public view but some are available to web:

https://landandmaritimeapps.dla.mil/Programs/MilSpec/asic.aspx.

FSC 5962 Vendor Item Drawing (VID)

- **5962 Vendor Item Drawing (VIDs):** These standardization documents are created to provide a procurement vehicle for enhanced commercial products via characterization and testing by the device manufacturers.

- **Benefits of VID:**
  - 5962 VID device requirements are a subset of the device requirements in MIL-PRF-38535 .
  - Use of VIDs will avoid the use of manufacturer generated specification control drawings (SCDs) and avoid the potential proliferation of non-standard products.
  - Extended temp range (-55°C to 125 °C).
  - Enhanced pedigree.
  - Obsolescence management.
  - Controlled baseline (i.e. one assembly site, one test site, one fab site.)
  - Some Radiation hardness assurance (RHA) VID parts are for nuclear and space Application.
  - For 5962 VIDs, the manufacturers' part number is the controlling Part Identification Number (PIN) V62/25605.

- **All Standardized VID documents and parts are available in the DLA website:**

https://landandmaritimeapps.dla.mil/programs/Smcr/

DLA Drawings

DLA Drawings :

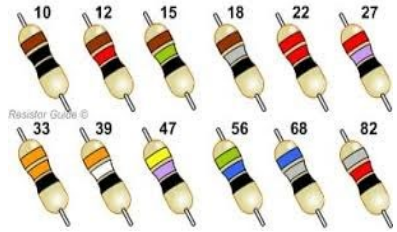
- DLA drawings are written to cover military type parts requiring special testing and screening requirements when a comparable standard part does not exist. In some instances, the DLA drawing will eventually be replaced by a superseding military specification part.

- Covering 24 + FSCs

- Mature devices
  - Military temp range(-55°C to 125 °C).
  - Documents are available on DLA website:

  https://landandmaritimeapps.dla.mil/programs/milspec/ListDwgs.aspx?DocTYPE=DSCCdwg

  https://landandmaritimeapps.dla.mil/programs/milspec/



- Used as “Quick response documents” or transitions documents to the Military services.
  - Precursor to MIL-SPECs

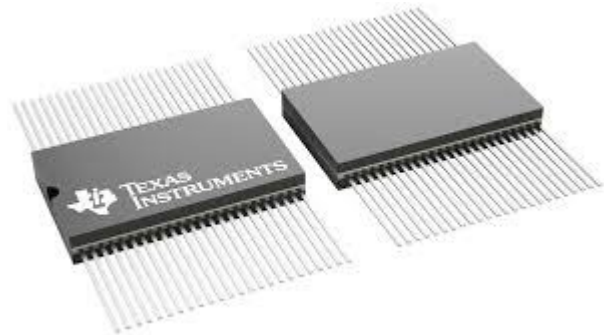
- Device requirements are a subset of Military Specification requirements.

- **MIL-PRF-38535 Revision N : Projected release date June 2026**

Major topics included in MIL-PRF-38535 revision N:

- **Non hermetic classes Y, N, and P.**
  - Findings as we qualify new non hermetic class certifications.
    - Using non-government standards vs MIL-STD-883
    - Au-Al wire bonding (class P)
    - Gold flash palladium lead finish thickness updates regarding alloy of NiPdAu
- **Update IGA Group D test and propose IGA Process monitor program**
  - Provide clarification of sample size .
  - Propose an Internal Gas Analysis (IGA) process monitor program.

- **Alternative to onsite wafer fabrication Audit**
  - Propose requirements for allowing the use of wafer fab facility in lieu of an onsite audit.
- **Adding gold wire (non-monometallic) for Class V (TG 25-02)**
  - DLA received request for classes V and P to allow Au-Al wire bonding?
  - Task group proposed new qualification/production test.
- **ESD**
  - Update to ESD control program at the wafer foundry.
- **Certificate of Compliance**
  - Delegated Signature Authorization
  - Submission Requirements for SMD Reviews and Revisions.

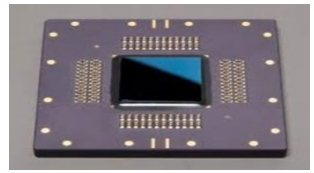


MIL-PRF-38535 provided Microcircuits Category/ Quality level classes :

Hermetic QML Devices:

Class Q (Hi-rel military application):

- Items which have been subjected to and passed all applicable requirements of this specification and applicable appendices including qualification testing, screening testing, and TCI/QCI inspections.
- All devices are documented in the Standard microcircuit drawing (SMD).

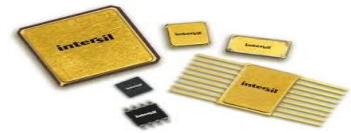


Class level B (M38510/slash sheet device):

- Items which have been subjected to and passed all applicable requirements of this specification including qualification testing, screening testing, and TCI/QCI inspections and are documented on a MIL-M-38510 specification sheet.

Class V (For Space application):

- Items that meet all the class Q requirements, and have been subjected to, and passed all applicable requirements of appendix B herein.
- All devices are documented in the Standard microcircuit drawing (SMD).



Class level S (for Space application M38510/slash sheet device):

- Items that meet all the class B requirements, and have been subjected to, and passed, all applicable requirements of appendix B herein and are documented on a MIL-M-38510 specification sheet.

Class M (883 compliant):

- Items which have been subjected to and passed all applicable requirements of appendix A herein and are documented on an SMD. This product is intended for military applications.

Class T (For specific application purposes)

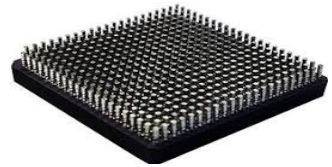
- Class T is a quality level whose requirements are defined by 3.4.8 herein and as documented on an SMD.

MIL-PRF-38535 provided Microcircuits Category/ Quality level classes

Non-hermetic QML Devices:

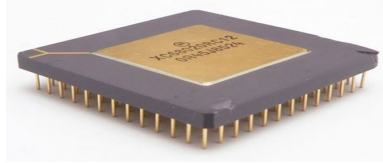
***Class N (PEM device for military application)*:**

- Items which have been subjected to and passed all applicable requirements of this specification including qualification testing, screening testing, and TCI/QCI inspections, and are encapsulated in plastic.
- All devices are documented in the Standard microcircuit drawing (SMD).



Class Y (for space application class level S device):

- A microcircuit employing a non-hermetic package, which meets all applicable requirements of this specification including qualification, screening and TCI/QCI requirements, and all applicable requirements of Appendix B herein.
- All devices are documented in the Standard microcircuit drawing (SMD).



Class P (PEM device for space application):

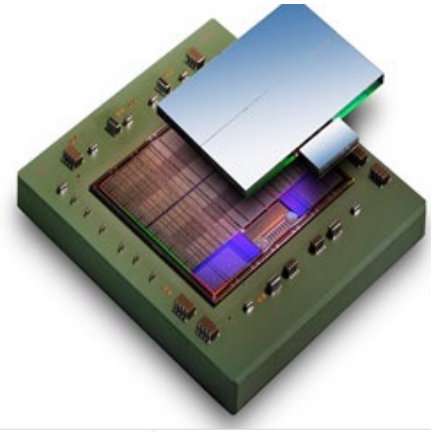
- A non-hermetic Plastic Encapsulated Microcircuit (PEM), which meets all applicable requirements of this specification including qualification, screening and TCI/QCI inspections, and all applicable requirements of Appendix B herein.
- All devices are documented in the Standard microcircuit drawing (SMD).

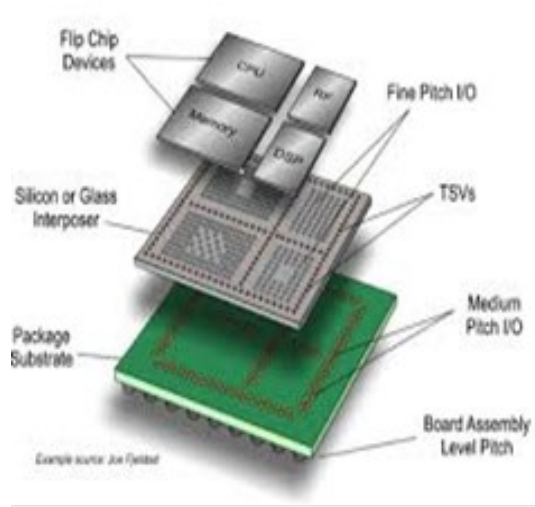
- **Standardized plastic Class P device with radiation hardened, high reliability for military terrestrial/avionics and space satellite applications.**

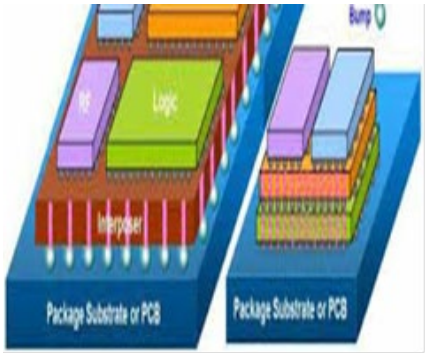
  - No pure tin.
  - Military temperature range environment (-55°C to 125 °C).
  - Will help to meet the current military and space systems longer life cycle needs, will prolong obsolescence, and will deter counterfeit devices from entering the supply chains.
  - Cost effective, light weight Class P plastic microcircuit devices will support the warfighter mission.
  - Current users include MDA, NASA, L3Harris, Raytheon, Lockheed, Northrup Grumman, National Instruments, SEAKR, Boeing, General Dynamics, Indian Space Research Organization, Viasat, Airbus, Honeywell, ExoTerra Resource.

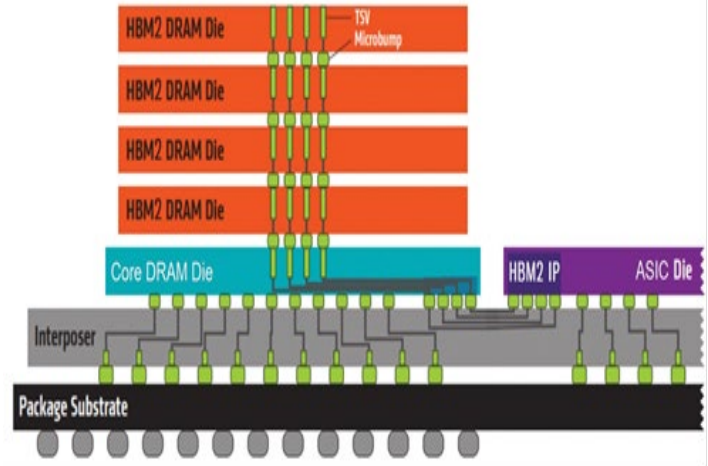
Advanced Technology Microcircuits (ATM) Devices Specification draft in-progress.

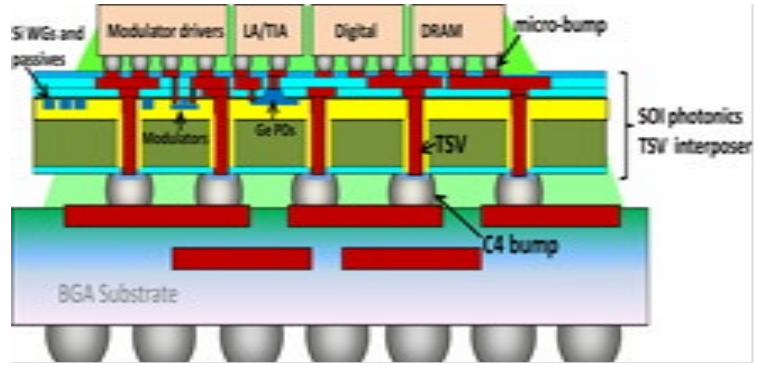
- JEDEC Task group working since 2021
- Devices are included:
  - Flip-chip 2.1D, 2.5D, 3D
  - System In Package (SIP)
  - Multi Chip Module (MCM)









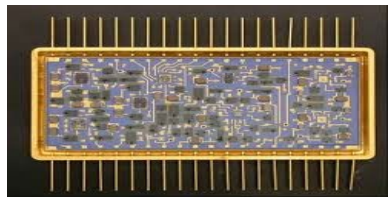


MIL-PRF-38534 Hybrid Microcircuits

- **MIL-PRF-38534 Revision M dated in 2025:**

Major topics included in MIL-PRF-38534 revision M:

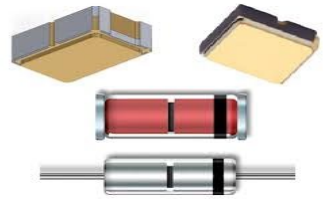
- Added requirement paragraph 3.9 to define when a hybrid microcircuit will be qualified to MIL-PRF-38534 vs MIL-PRF-38535.



- Hermetic and non-hermetic class devices.
- Replaced the current definition of production lot to clarify lot homogeneity.
- Updated test sample preparation to better define and clarify when test samples for active elements are being prepared with similar assembly methods.
- Updated test sample preparation to better define and clarify when test samples for passive elements are being prepared with similar assembly methods.

MIL-PRF-19500
Semiconductor Devices Program

- MIL-PRF-19500 (FSC 5961: semiconductor device) program supported by:



- 17 qualified manufacturers.

- 32+ certified fabrications and assembly facilities.

- Supplying 26,010+ transistors, diode and optocoupler types of devices for supporting warfighters and successful space mission.

- New technology RHA Gallium Nitride (GaN) semiconductor in MIL-PRF-19500 specifications available for harsh environment, low earth orbit (LEO), geosynchronous equatorial orbit (GEO), and deep-space exploratory missions.

- DLA total purchase value in 2025: $12.2 million.

DLA Radiation Hardness Assurance (RHA) program

Program

- MIL-PRF-38535/38534 RHA SMD :
  - 1,118 Active SMDs available with RHA requirements.
  - 10,296 RHA devices available.
  - 20 RHA QML device suppliers are currently available.

- MIL-PRF-19500 RHA slash sheets:
  - 175+ slash sheets available with RHA requirements.
  - 7 RHA QPL device suppliers are currently available.

- Total ionizing dose(TID) test – TM 1019 of MIL-STD-883 and MIL-STD-750

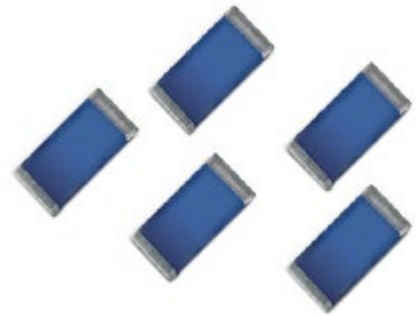
- Neutron/ Displacement damage test-TM 1017 of MIL-STD-883
- High dose rate latch-up test – TM 1020 of MIL-STD-883
- High dose rate upset test – TM 1021 of MIL-STD-883
- Dose rate survivability test – TM 1023 of MIL-STD-883
- Heavy ion SEE (SEL/SEB/SEGR/SEU/SET/SEFI) test shall follow ASTM F1192 or JESD57
- Proton test shall follow JESD234
- TM1080 of MIL-STD-750 for SEE (SEB/SEGR) semiconductor devices.
- Proposed TM1086 of MIL-STD-750 for SEE (SEB) testing for Schottky diode devices in-progress.

DLA Weapons Support Columbus buy $ values

- **FSC 5905 : Resistors**

- DLA manages high reliability space level Resistors spec.
- MIL-PRF-39007 Fixed Wirewound, ER.

- MIL-PRF-55182 Fixed Film, Precision, ER.
- MIL-PRF-55342 Fixed Film, Chip, ER.

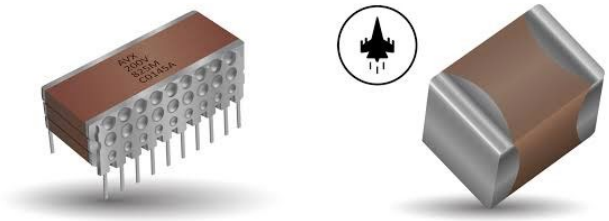


- 151, 477 NSNs Resistors Parts.
- 2025 total purchase value $15.05 million.

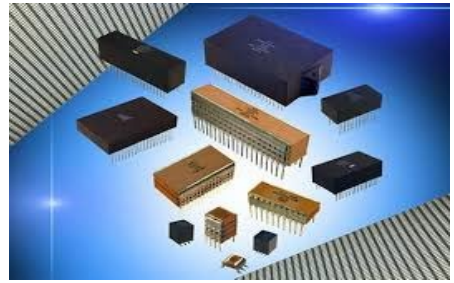
DLA Weapons Support Columbus buy $ values

- **FSC 5910: Capacitors**

- DLA manages 213 specifications for manufacturing high reliability capacitors for military and space application.
- Capacitors are Ceramic, Tantalum, Film, Aluminum Oxide, Mica, Planar Array, and Trimmer .
- DLA supply chains contains over 28,000 NSNs capacitors.



- New technology MIL-PRF-STACK spec developed for stacked capacitor assemblies utilizing extended range ceramic capacitors for higher capacitance values like those in MIL-PRF-32535.
- High reliability T level capacitors for MIL-PRF-32700 are intended use for space, missile, and other high reliability applications.



- DLA total purchase value in 2025 $15.05 million.

DLA Weapons Support Columbus buy $ values

- **FSC 6135 (non-rechargeable) and 6140 (rechargeable):**
  - 4,429 NSNs parts
  - $198.11 million purchase in 2025

- **FSC 5935 Connectors (R.F. connectors, Circular, Rectangular)**
  - 43,869 NSNs parts
  - 2025 purchase $ 62.60 million.

- **FSC 5960 Electron Tube, microwave**
  - 4,643 NSNs parts
  - 2025 purchase: $ 15.60 million.

Military Standards Test Method

- **MIL-STD-883 : Test method for Microcircuits devices**
  - MIL-STD-883-1 contains: 28 Environmental test methods.
  - MIL-STD-883-2 contains: 35 Mechanical test methods.
  - MIL-STD-883-3 contains: 24 Electrical test (digital) methods.
  - MIL-STD-883-4 contains: 7 Electrical test (Linear) methods.
  - MIL-STD-883-5 contains: 13 Test procedures for qualification and evaluations.

- **MIL−STD−750 : Test methods for Semiconductor Devices**.
  - MIL−STD−750−1 − Environmental Test Methods For Semiconductor Devices.
  - MIL−STD−750−2 − Mechanical Test Methods For Semiconductor Devices.
  - MIL−STD−750−3 − Electrical Characteristics Tests for Bipolar, MOSFET, and GaAs Transistors.
  - MIL−STD−750−4 − Electrical Characteristics Tests for Diodes, Thyristors, and Tunnel Diodes.
  - MIL−STD−750−5 − High Reliability Space Application Test Methods For Semiconductor Devices.

- **MIL−STD−202 : Test methods for Passive components**
  - MIL-STD-202-1 contains: 12 Environmental test methods.
  - MIL-STD-202-2 contains: 17 Physical characteristics test methods.
  - MIL-STD-202-3 contains: 12 Electrical characteristics test methods.

- **MIL−STD−1580:** Test methods for Destructive Physical Analysis for Electronic, Electromagnetic, and Electromechanical Part.

BACKUP SLIDES

What is the DoD Specs and Standards Program?

- Formal program established by the DoD to standardize requirements for parts and material.
- Established by Congress (10 U.S.C. 2451-2457)
- Executed by the DoD (DoDI 4120-24)
- Participation by the various military departments and defense agencies (e.g., DLA)

MIL-PRF-38535 devices classes

Example Device Marking Options	Device Class Designator in PIN 1/	Potential device class 2/	Equivalent Class Level 3/	Device Certification Mark 4/	Listing Location	Test Optimization
5962-9912301MXX	M	M Hermetic	Level B, Self Certification, Meets requirements of 5004 and 5005, No TRB	"C"	MIL-HDBK-103	**No**
		Q Hermetic	Level B, Certified and Qualified, Has TRB	"Q" or "QML"	QML Section 1 and MIL-HDBK-103	**Yes**
5962-9912401QXX or M38510/12301BXX	Q or B	Q Hermetic	Level B, Certified and Qualified, Has TRB	"Q" or "QML"	QML Section 1 and MIL-HDBK-103	**Yes**
5962-9912501VXX or M38510/12301SXX	V or S	V Hermetic	Level S, Meets QML Requirements and Appendix B of MIL-PRF-38535, Has TRB	"Q" or "QML"	QML Section 1 and MIL-HDBK-103	**Yes**
5962-9912301XX or 8502501XX	No Marking Level Designator	M Hermetic	Level B, Self Certification, Meets requirements of 5004 and 5005, No TRB	"C"	MIL-HDBK-103	**No**
		Q or B Hermetic	Level B, Certified and Qualified, Has TRB	"Q" or "QML"	QML Section 1 and MIL-HDBK-103	**Yes**
5962-9912301TXX	T	T Hermetic	For satellite applications, Certified and qualified manufacturer, Has TRB, manufacturer's testing flow specified in Class T QM Plan	"Q" or "QML"	QML Section 1 and MIL-HDBK-103	**See QM Plan 5/**
5962-9912501YXX	Y	Y Non Hermetic (Ceramic or Organic) Flip Chip only	Level S, Meets QML Requirements and Appendix B of MIL-PRF-38535, Has TRB	"Q" or "QML"	QML Section 1 and MIL-HDBK-103	**Yes**
5962-99121301NXX	N	N Non Hermetic (PEMs Only)	Level B, Certified and Qualified, Has TRB Appropriate requirements for military, terrestrial and avionics application	"Q" or "QML"	QML Section 1 and MIL-HDBK-103	**Yes**
5962-99121301PXX	**P**	**P Non Hermetic (PEMs Only)**	**Level S, Meets QML Requirements and Appendix B of MIL-PRF-38535, Has TRB Appropriate requirements for space application**	**"Q" or "QML"**	**QML Section 1 and MIL-HDBK-103**	**Yes**

New Technology Activities

- **New Class P (Space application) devices**: New PEM class P SMD devices released under MIL-PRF-38535. Generally, class P devices are plastic, RHA TID level 50-100 krads (HDR and LDR tested) and Heavy ion SEE tested for Military and Space application .

- **Microchip (Microsemi SOC) is pursuing organic class Y QML HPSC processor devices.** High-Performance Spaceflight Computing (HPSC) processor that will provide at least 100 times the computational capacity of current spaceflight computers. DLA - QA is audited Microchip (Microsemi SOC) facilities, and they have pipeline for qualifying class Y Flip chip RTG type product and many more newer technology devices.

- New RHA Vendor Item Drawing (VID) also available for microcircuit devices.

- **New Advanced Technology Microcircuits MIL-PRF-ATM:** Task group meeting held biweekly led by Eli Minson. TG sent preliminary draft text for ATM specification to DLA. DLA is working on MIL-PRF-ATM preliminary draft. ATM devices are greater than 2D (2.1D, 2.5D,3D) , SIP, and will be supplied as SMD QML device. DLA prepared draft ATM SMD boilerplate.

Finding SPECS and Standards

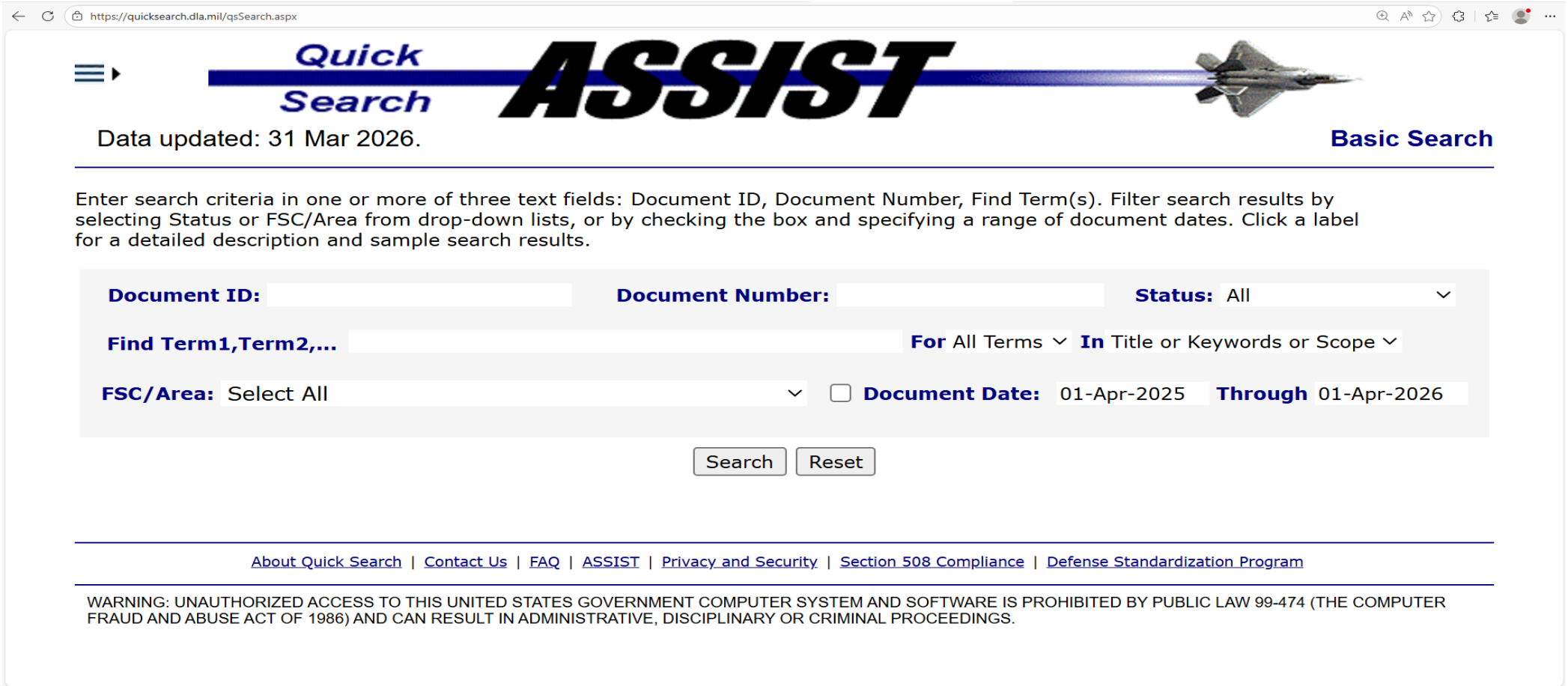
DLA Specs and Standards are available from the following DLA Websites:

- DLA Weapons Support Columbus weblink: https://landandmaritimeapps.dla.mil/programs/milspec/
- DLA ASSIST weblink: https://quicksearch.dla.mil

Find specification, standards and QPL Parts in ASSIST

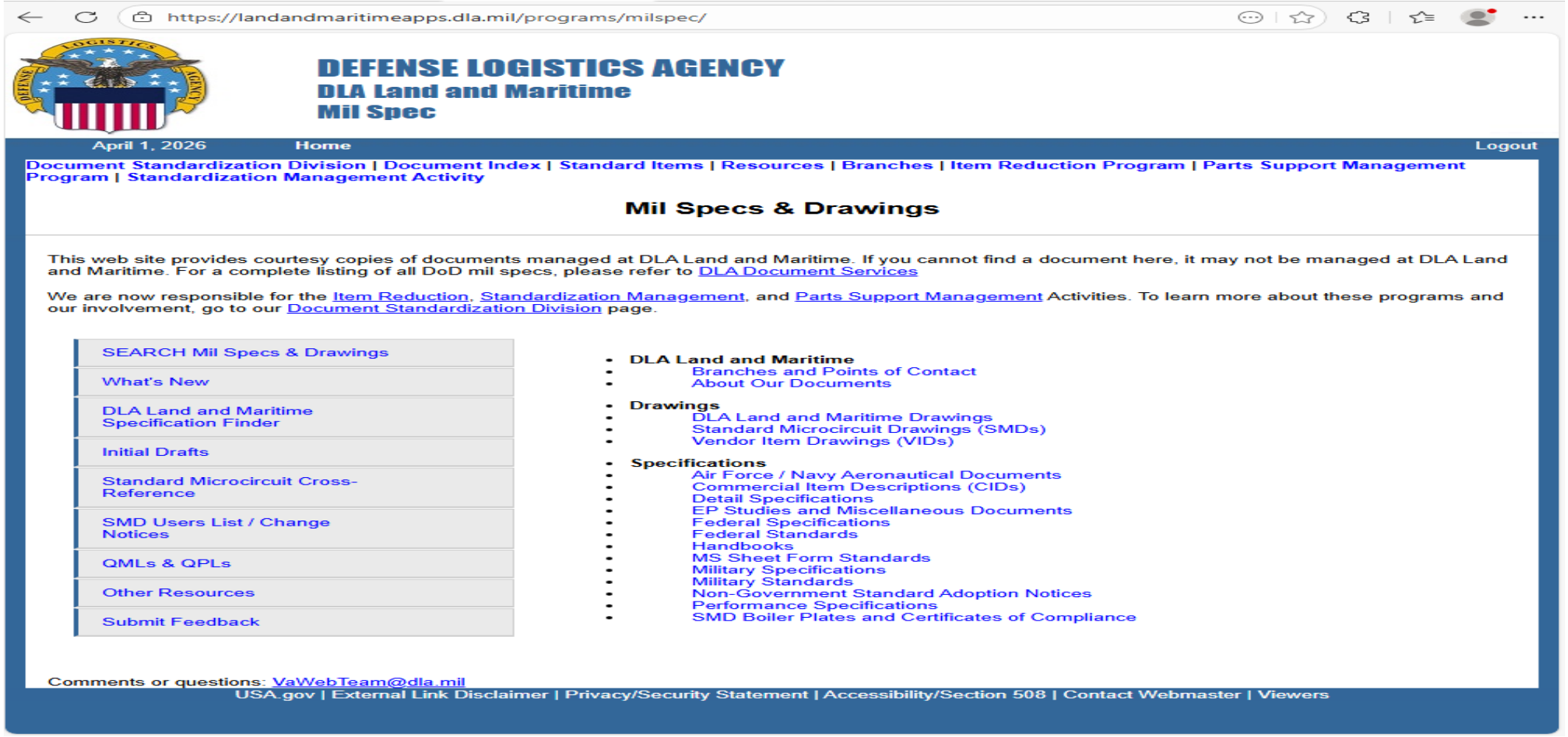
Acquisition Streamlining and Standardization Information System (ASSIST) weblink:

https://quicksearch.dla.mil/



Find MIL Specs , SMDs & Drawings in DLA website

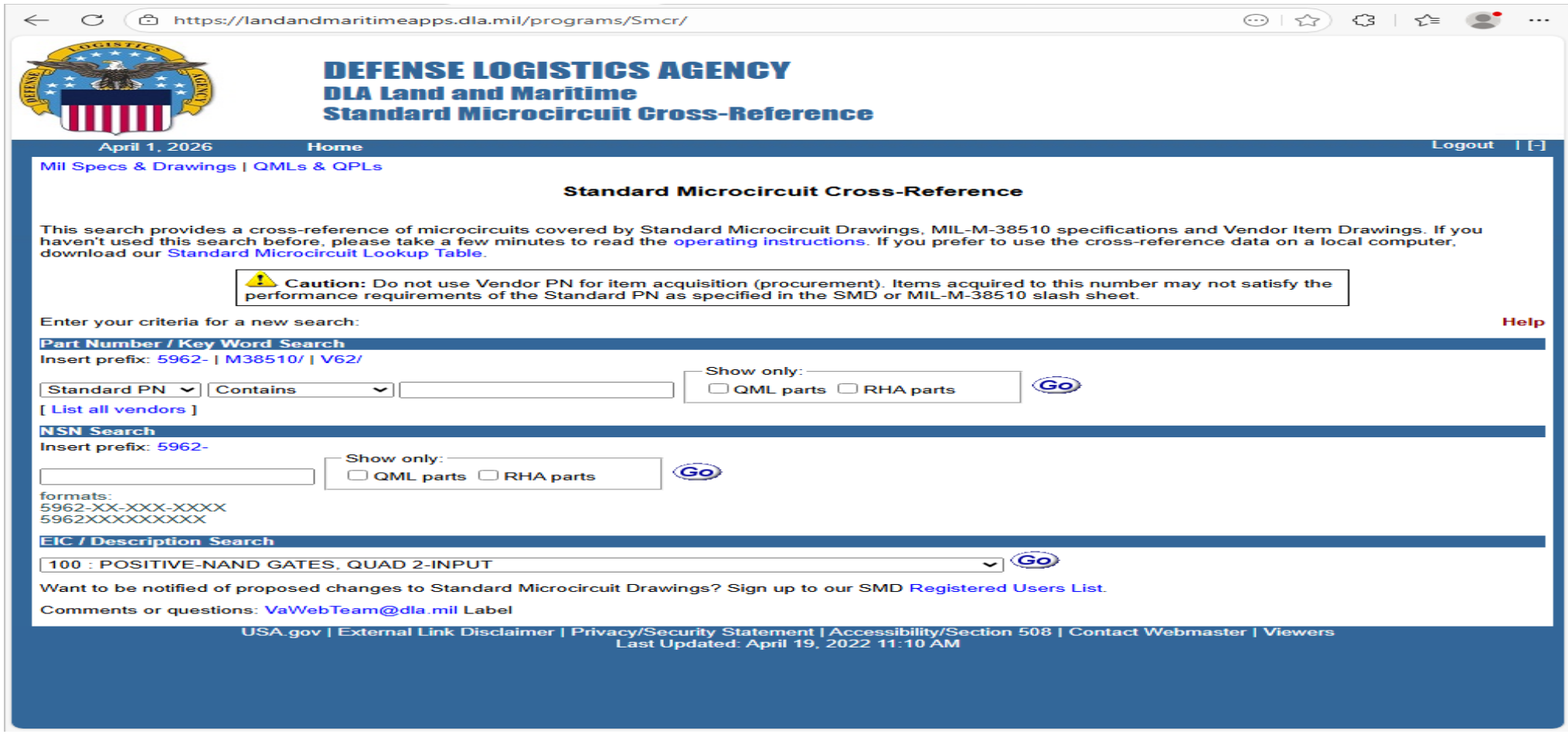
DLA Weapons Support Columbus MIL Specs and standards website:
https://landandmaritimeapps.dla.mil/programs/milspec/



5962 SMD, VID Parts and Vendor search (SMCR) website

FSC 5962 SMD, M38510, VID parts and Vendor search website:

https://landandmaritimeapps.dla.mil/programs/Smcr/



Qualified Product Database (QPD)

QPD parts search as an example of MIL-PRF-19500 transistors parts:-

https://qpldocs.dla.mil/search/parts.aspx?qpl=630&param=JAN2N2221AUA&type=8

or

https://qpldocs.dla.mil/default.aspx

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Question ????